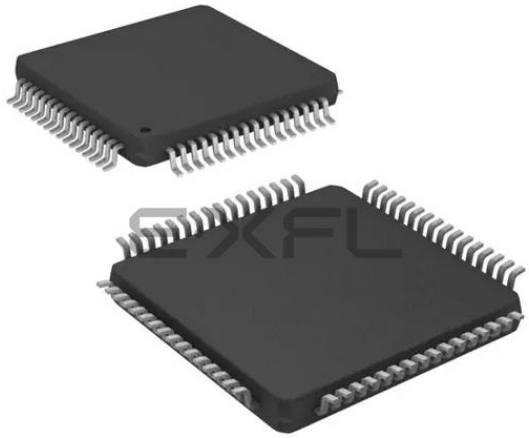


Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	40MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, HLVD, POR, PWM, WDT
Number of I/O	54
Program Memory Size	48KB (24K x 16)
Program Memory Type	FLASH
EEPROM Size	1K x 8
RAM Size	3936 x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 5.5V
Data Converters	A/D 12x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-TQFP
Supplier Device Package	64-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic18lf6527t-i-pt

Note the following details of the code protection feature on Microchip devices:

- Microchip products meet the specification contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is one of the most secure families of its kind on the market today, when used in the intended manner and under normal conditions.
- There are dishonest and possibly illegal methods used to breach the code protection feature. All of these methods, to our knowledge, require using the Microchip products in a manner outside the operating specifications contained in Microchip's Data Sheets. Most likely, the person doing so is engaged in theft of intellectual property.
- Microchip is willing to work with the customer who is concerned about the integrity of their code.
- Neither Microchip nor any other semiconductor manufacturer can guarantee the security of their code. Code protection does not mean that we are guaranteeing the product as "unbreakable."

Code protection is constantly evolving. We at Microchip are committed to continuously improving the code protection features of our products. Attempts to break Microchip's code protection feature may be a violation of the Digital Millennium Copyright Act. If such acts allow unauthorized access to your software or other copyrighted work, you may have a right to sue for relief under that Act.

Trademarks

QUALITY MANAGEMENT SYSTEM
CERTIFIED BY DNV
ISO/TS 16949:2002

Microchip received ISO/TS-16949:2002 certification for its worldwide headquarters, design and wafer fabrication facilities in Chandler and Tempe, Arizona; Gresham, Oregon and design centers in California and India. The Company's quality system processes and procedures are for its PIC® MCUs and dsPIC® DSCs, KEELOQ® code hopping devices, Serial EEPROMs, microperipherals, nonvolatile memory and analog products. In addition, Microchip's quality system for the design and manufacture of development systems is ISO 9001:2000 certified.

TABLE 1-3: PIC18F6527/6622/6627/6722 PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number	Pin Type	Buffer Type	Description
	TQFP			
				PORTF is a bidirectional I/O port.
RF0/AN5	18			
RF0		I/O	ST	Digital I/O.
AN5		I	Analog	Analog input 5.
RF1/AN6/C2OUT	17			
RF1		I/O	ST	Digital I/O.
AN6		I	Analog	Analog input 6.
C2OUT		O	—	Comparator 2 output.
RF2/AN7/C1OUT	16			
RF2		I/O	ST	Digital I/O.
AN7		I	Analog	Analog input 7.
C1OUT		O	—	Comparator 1 output.
RF3/AN8	15			
RF3		I/O	ST	Digital I/O.
AN8		I	Analog	Analog input 8.
RF4/AN9	14			
RF4		I/O	ST	Digital I/O.
AN9		I	Analog	Analog input 9.
RF5/AN10/CVREF	13			
RF5		I/O	ST	Digital I/O.
AN10		I	Analog	Analog input 10.
CVREF		O	Analog	Comparator reference voltage output.
RF6/AN11	12			
RF6		I/O	ST	Digital I/O.
AN11		I	Analog	Analog input 11.
RF7/$\overline{SS1}$	11			
RF7		I/O	ST	Digital I/O.
$\overline{SS1}$		I	TTL	SPI slave select input.

Legend: TTL = TTL compatible input CMOS = CMOS compatible input or output
ST = Schmitt Trigger input with CMOS levels Analog = Analog input
I = Input O = Output
P = Power I^2C™ = I^2C/SMBus input buffer

Note 1: Default assignment for ECCP2 when Configuration bit, CCP2MX, is set.
2: Alternate assignment for ECCP2 when Configuration bit, CCP2MX, is cleared.

REGISTER 10-2: INTCON2: INTERRUPT CONTROL REGISTER 2

R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
$\overline{\text{RBPU}}$	INTEDG0	INTEDG1	INTEDG2	INTEDG3	TMR0IP	INT3IP	RBIP
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 **$\overline{\text{RBPU}}$:** PORTB Pull-up Enable bit
1 = All PORTB pull-ups are disabled
0 = PORTB pull-ups are enabled by individual port latch values

bit 6 **INTEDG0:** External Interrupt 0 Edge Select bit
1 = Interrupt on rising edge
0 = Interrupt on falling edge

bit 5 **INTEDG1:** External Interrupt 1 Edge Select bit
1 = Interrupt on rising edge
0 = Interrupt on falling edge

bit 4 **INTEDG2:** External Interrupt 2 Edge Select bit
1 = Interrupt on rising edge
0 = Interrupt on falling edge

bit 3 **INTEDG3:** External Interrupt 3 Edge Select bit
1 = Interrupt on rising edge
0 = Interrupt on falling edge

bit 2 **TMR0IP:** TMR0 Overflow Interrupt Priority bit
1 = High priority
0 = Low priority

bit 1 **INT3IP:** INT3 External Interrupt Priority bit
1 = High priority
0 = Low priority

bit 0 **RBIP:** RB Port Change Interrupt Priority bit
1 = High priority
0 = Low priority

Note: Interrupt flag bits are set when an interrupt condition occurs, regardless of the state of its corresponding enable bit or the global interrupt enable bit. User software should ensure the appropriate interrupt flag bits are clear prior to enabling an interrupt. This feature allows for software polling.

REGISTER 10-11: IPR2: PERIPHERAL INTERRUPT PRIORITY REGISTER 2

R/W-1	R/W-1	U-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
OSCFIP	CMIP	—	EEIP	BCL1IP	HLVDIP	TMR3IP	CCP2IP
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 7 **OSCFIP:** Oscillator Fail Interrupt Priority bit
1 = High priority
0 = Low priority

bit 6 **CMIP:** Comparator Interrupt Priority bit
1 = High priority
0 = Low priority

bit 5 **Unimplemented:** Read as ‘0’

bit 4 **EEIP:** Interrupt Priority bit
1 = High priority
0 = Low priority

bit 3 **BCL1IP:** MSSP1 Bus Collision Interrupt Priority bit
1 = High priority
0 = Low priority

bit 2 **HLVDIP:** High/Low-Voltage Detect Interrupt Priority bit
1 = High priority
0 = Low priority

bit 1 **TMR3IP:** TMR3 Overflow Interrupt Priority bit
1 = High priority
0 = Low priority

bit 0 **CCP2IP:** ECCP2 Interrupt Priority bit
1 = High priority
0 = Low priority

TABLE 11-1: PORTA FUNCTIONS

Pin Name	Function	TRIS Setting	I/O	I/O Type	Description
RA0/AN0	RA0	0	O	DIG	LATA<0> data output; not affected by analog input.
		1	I	TTL	PORTA<0> data input; disabled when analog input enabled.
	AN0	1	I	ANA	A/D input channel 0. Default input configuration on POR; does not affect digital output.
RA1/AN1	RA1	0	O	DIG	LATA<1> data output; not affected by analog input.
		1	I	TTL	PORTA<1> data input; disabled when analog input enabled.
	AN1	1	I	ANA	A/D input channel 1. Default input configuration on POR; does not affect digital output.
RA2/AN2/VREF-	RA2	0	O	DIG	LATA<2> data output; not affected by analog input.
		1	I	TTL	PORTA<2> data input. Disabled when analog functions enabled.
	AN2	1	I	ANA	A/D input channel 2. Default input configuration on POR.
	VREF-	1	I	ANA	Comparator voltage reference low input and A/D voltage reference low input.
RA3/AN3/VREF+	RA3	0	O	DIG	LATA<3> data output; not affected by analog input.
		1	I	TTL	PORTA<3> data input; disabled when analog input enabled.
	AN3	1	I	ANA	A/D input channel 3. Default input configuration on POR.
	VREF+	1	I	ANA	Comparator voltage reference high input and A/D voltage reference high input.
RA4/T0CKI	RA4	0	O	DIG	LATA<4> data output.
		1	I	ST	PORTA<4> data input; default configuration on POR.
	T0CKI	x	I	ST	Timer0 clock input.
RA5/AN4/HLVDIN	RA5	0	O	DIG	LATA<5> data output; not affected by analog input.
		1	I	TTL	PORTA<5> data input; disabled when analog input enabled.
	AN4	1	I	ANA	A/D input channel 4. Default configuration on POR.
	HLVDIN	1	I	ANA	High/Low-Voltage Detect external trip point input.
OSC2/CLKO/RA6	OSC2	x	O	ANA	Main oscillator feedback output connection (XT, HS, HSPLL and LP modes).
	CLKO	x	O	DIG	System cycle clock output (FOSC/4) in all oscillator modes except RC, INTIO7 and EC.
	RA6	0	O	DIG	LATA<6> data output. Enabled in RCIO, INTIO2 and ECIO modes only.
		1	I	TTL	PORTA<6> data input. Enabled in RCIO, INTIO2 and ECIO modes only.
OSC1/CLKI/RA7	OSC1	x	I	ANA	Main oscillator input connection.
	CLKI	x	I	ANA	Main clock input connection.
	RA7	0	O	DIG	LATA<7> data output. Disabled in external oscillator modes.
		1	I	TTL	PORTA<7> data input. Disabled in external oscillator modes.

Legend: PWR = Power Supply, O = Output, I = Input, ANA = Analog Signal, DIG = Digital Output, ST= Schmitt Buffer Input, TTL = TTL Buffer Input, x = Don't care (TRIS bit does not affect port direction or is overridden for this option).

TABLE 11-2: SUMMARY OF REGISTERS ASSOCIATED WITH PORTA

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Reset Values on page
PORTA	RA7(1)	RA6(1)	RA5	RA4	RA3	RA2	RA1	RA0	61
LATA	LATA7(1)	LATA6(1)	LATA5	LATA4	LATA3	LATA2	LATA1	LATA0	60
TRISA	TRISA7(1)	TRISA6(1)	TRISA5	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	60
ADCON1	—	—	VCFG1	VCFG0	PCFG3	PCFG2	PCFG1	PCFG0	59

Legend: — = unimplemented, read as '0'. Shaded cells are not used by PORTA.

Note 1: RA<7:6> and their associated latch and data direction bits are enabled as I/O pins based on oscillator configuration; otherwise, they are read as '0'.

TABLE 11-3: PORTB FUNCTIONS

Pin Name	Function	TRIS Setting	I/O	I/O Type	Description
RB0/INT0/FLT0	RB0	0	O	DIG	LATB<0> data output.
		1	I	TTL	PORTB<0> data input; weak pull-up when $\overline{\text{RBPU}}$ bit is cleared.
	INT0	1	I	ST	External interrupt 0 input.
	FLT0	1	I	ST	ECCPx PWM Fault input, enabled in software.
RB1/INT1	RB1	0	O	DIG	LATB<1> data output.
		1	I	TTL	PORTB<1> data input; weak pull-up when $\overline{\text{RBPU}}$ bit is cleared.
	INT1	1	I	ST	External interrupt 1 input.
RB2/INT2	RB2	0	O	DIG	LATB<2> data output.
		1	I	TTL	PORTB<2> data input; weak pull-up when $\overline{\text{RBPU}}$ bit is cleared.
	INT2	1	I	ST	External interrupt 2 input.
RB3/INT3/ ECCP2/P2A	RB3	0	O	DIG	LATB<3> data output.
		1	I	TTL	PORTB<3> data input; weak pull-up when $\overline{\text{RBPU}}$ bit is cleared and capture input is disabled.
	INT3	1	I	ST	External interrupt 3 input.
	ECCP2(1)	0	O	DIG	ECCP2 compare output and ECCP2 PWM output. Takes priority over port data.
		1	I	ST	ECCP2 capture input.
	P2A(1)	0	O	DIG	ECCP2 Enhanced PWM output, channel A. May be configured for tri-state during Enhanced PWM shutdown events. Takes priority over port data.
RB4/KBI0	RB4	0	O	DIG	LATB<4> data output.
		1	I	TTL	PORTB<4> data input; weak pull-up when $\overline{\text{RBPU}}$ bit is cleared.
	KBI0	1	I	TTL	Interrupt-on-pin change.
RB5/KBI1/PGM	RB5	0	O	DIG	LATB<5> data output
		1	I	TTL	PORTB<5> data input; weak pull-up when $\overline{\text{RBPU}}$ bit is cleared.
	KBI1	1	I	TTL	Interrupt-on-pin change.
	PGM	x	I	ST	Single-Supply Programming mode entry (ICSP). Enabled by LVP Configuration bit; all other pin functions disabled.
RB6/KBI2/PGC	RB6	0	O	DIG	LATB<6> data output.
		1	I	TTL	PORTB<6> data input; weak pull-up when $\overline{\text{RBPU}}$ bit is cleared.
	KBI2	1	I	TTL	Interrupt-on-pin change.
	PGC	x	I	ST	Serial execution (ICSP™) clock input for ICSP and ICD operation(2).
RB7/KBI3/PGD	RB7	0	O	DIG	LATB<7> data output.
		1	I	TTL	PORTB<7> data input; weak pull-up when $\overline{\text{RBPU}}$ bit is cleared.
	KBI3	1	I	TTL	Interrupt-on-pin change.
	PGD	x	O	DIG	Serial execution data output for ICSP and ICD operation(2).
		x	I	ST	Serial execution data input for ICSP and ICD operation(2).

Legend: PWR = Power Supply, O = Output, I = Input, ANA = Analog Signal, DIG = Digital Output, ST = Schmitt Buffer Input, TTL = TTL Buffer Input, x = Don't care (TRIS bit does not affect port direction or is overridden for this option).

Note 1: Alternate assignment for ECCP2 when the CCP2MX Configuration bit is cleared (Microprocessor, Extended Microcontroller and Microcontroller with Boot Block modes, 80-pin devices only). Default assignment is RC1.

2: All other pin functions are disabled when ICSP or ICD operations are enabled.

12.0 TIMER0 MODULE

The Timer0 module incorporates the following features:

- Software selectable operation as a timer or counter in both 8-bit or 16-bit modes
- Readable and writable registers
- Dedicated 8-bit, software programmable prescaler
- Selectable clock source (internal or external)
- Edge select for external clock
- Interrupt-on-overflow

The T0CON register (Register 12-1) controls all aspects of the module's operation, including the prescale selection. It is both readable and writable.

A simplified block diagram of the Timer0 module in 8-bit mode is shown in Figure 12-1. Figure 12-2 shows a simplified block diagram of the Timer0 module in 16-bit mode.

REGISTER 12-1: T0CON: TIMER0 CONTROL REGISTER

R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
TMR0ON	T08BIT	T0CS	T0SE	PSA	T0PS2	T0PS1	T0PS0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 **TMR0ON:** Timer0 On/Off Control bit
1 = Enables Timer0
0 = Stops Timer0

bit 6 **T08BIT**: Timer0 8-bit/16-bit Control bit
1 = Timer0 is configured as an 8-bit timer/counter
0 = Timer0 is configured as a 16-bit timer/counter

bit 5 **T0CS**: Timer0 Clock Source Select bit
1 = Transition on T0CKI pin
0 = Internal instruction cycle clock (CLKO)

bit 4 **T0SE**: Timer0 Source Edge Select bit
1 = Increment on high-to-low transition on T0CKI pin
0 = Increment on low-to-high transition on T0CKI pin

bit 3 **PSA**: Timer0 Prescaler Assignment bit
1 = TImer0 prescaler is NOT assigned. Timer0 clock input bypasses prescaler.
0 = Timer0 prescaler is assigned. Timer0 clock input comes from prescaler output.

bit 2-0 **T0PS<2:0>**: Timer0 Prescaler Select bits
111 = 1:256 Prescale value
110 = 1:128 Prescale value
101 = 1:64 Prescale value
100 = 1:32 Prescale value
011 = 1:16 Prescale value
010 = 1:8 Prescale value
001 = 1:4 Prescale value
000 = 1:2 Prescale value

NOTES:

19.4.17.2 Bus Collision During a Repeated Start Condition

During a Repeated Start condition, a bus collision occurs if:

a) A low level is sampled on SDAx when SCLx goes from low level to high level.

b) SCLx goes low before SDAx is asserted low, indicating that another master is attempting to transmit a data '1'.

When the user deasserts SDAx and the pin is allowed to float high, the BRG is loaded with SSPxADD<6:0> and counts down to '0'. The SCLx pin is then deasserted and when sampled high, the SDAx pin is sampled.

If SDAx is low, a bus collision has occurred (i.e., another master is attempting to transmit a data '0', Figure 19-29). If SDAx is sampled high, the BRG is reloaded and begins counting. If SDAx goes from high-to-low before the BRG times out, no bus collision occurs because no two masters can assert SDAx at exactly the same time.

If SCLx goes from high-to-low before the BRG times out and SDAx has not already been asserted, a bus collision occurs. In this case, another master is attempting to transmit a data '1' during the Repeated Start condition (see Figure 19-30).

If, at the end of the BRG time-out, both SCLx and SDAx are still high, the SDAx pin is driven low and the BRG is reloaded and begins counting. At the end of the count, regardless of the status of the SCLx pin, the SCLx pin is driven low and the Repeated Start condition is complete.

FIGURE 19-29: BUS COLLISION DURING A REPEATED START CONDITION (CASE 1)

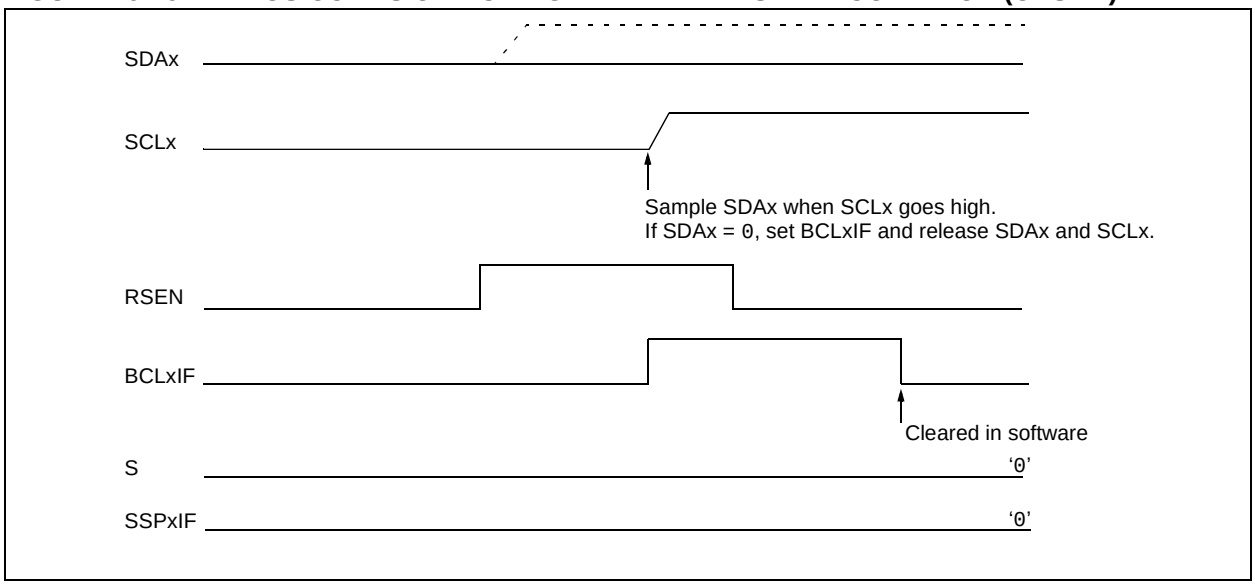
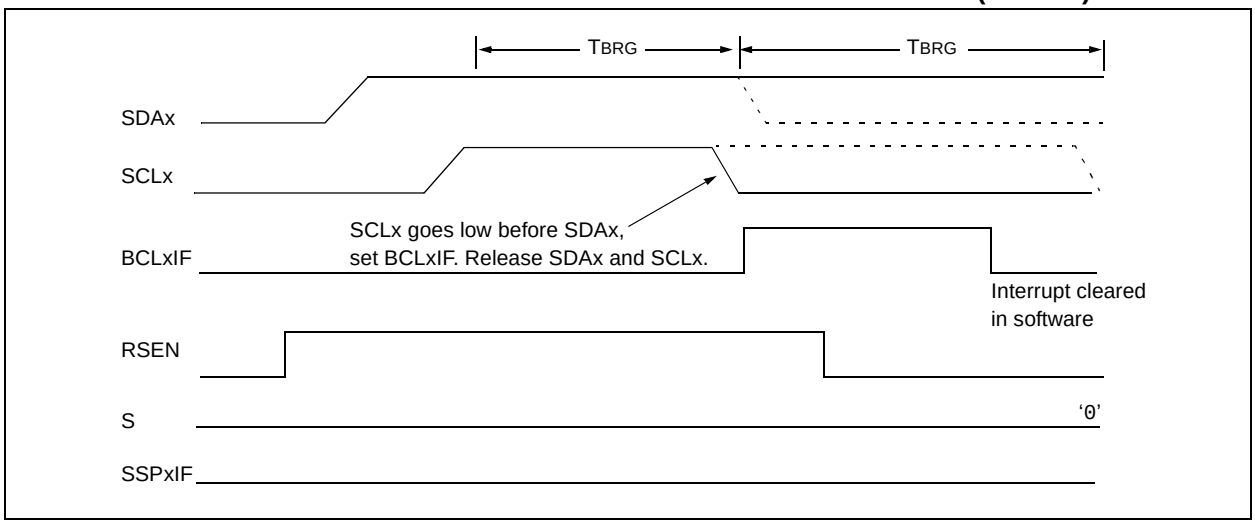


FIGURE 19-30: BUS COLLISION DURING REPEATED START CONDITION (CASE 2)



REGISTER 20-2: RCSTAx: RECEIVE STATUS AND CONTROL REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R-0	R-0	R-x
SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 **SPEN:** Serial Port Enable bit
1 = Serial port enabled (configures RXx/DTx and TXx/CKx pins as serial port pins)
0 = Serial port disabled (held in Reset)

bit 6 **RX9:** 9-bit Receive Enable bit
1 = Selects 9-bit reception
0 = Selects 8-bit reception

bit 5 **SREN:** Single Receive Enable bit
Asynchronous mode:
Don't care.
Synchronous mode – Master:
1 = Enables single receive
0 = Disables single receive
This bit is cleared after reception is complete.
Synchronous mode – Slave:
Don't care.

bit 4 **CREN:** Continuous Receive Enable bit
Asynchronous mode:
1 = Enables receiver
0 = Disables receiver
Synchronous mode:
1 = Enables continuous receive until enable bit CREN is cleared (CREN overrides SREN)
0 = Disables continuous receive

bit 3 **ADDEN:** Address Detect Enable bit
Asynchronous mode 9-bit (RX9 = 1):
1 = Enables address detection, enables interrupt and loads the receive buffer when RSRx<8> is set
0 = Disables address detection, all bytes are received and ninth bit can be used as parity bit
Asynchronous mode 9-bit (RX9 = 0):
Don't care.

bit 2 **FERR:** Framing Error bit
1 = Framing error (can be updated by reading RCREGx register and receiving next valid byte)
0 = No framing error

bit 1 **OERR:** Overrun Error bit
1 = Overrun error (can be cleared by clearing bit CREN)
0 = No overrun error

bit 0 **RX9D:** 9th bit of Received Data
This can be address/data bit or a parity bit and must be calculated by user firmware.

21.1 A/D Acquisition Requirements

For the A/D converter to meet its specified accuracy, the charge holding capacitor (C_{HOLD}) must be allowed to fully charge to the input channel voltage level. The analog input model is shown in Figure 21-3. The source impedance (R_S) and the internal sampling switch (R_{SS}) impedance directly affect the time required to charge the capacitor C_{HOLD}. The sampling switch (R_{SS}) impedance varies over the device voltage (V_{DD}). The source impedance affects the offset voltage at the analog input (due to pin leakage current). **The maximum recommended impedance for analog sources is 2.5 kΩ.** After the analog input channel is selected (changed), the channel must be sampled for at least the minimum acquisition time before starting a conversion.

Note:	When the conversion is started, the holding capacitor is disconnected from the input pin.

To calculate the minimum acquisition time, Equation 21-1 may be used. This equation assumes that 1/2 LSb error is used (1024 steps for the A/D). The 1/2 LSb error is the maximum error allowed for the A/D to meet its specified resolution.

Example 21-3 shows the calculation of the minimum required acquisition time T_{ACQ}. This calculation is based on the following application system assumptions:

C_{HOLD}	=	25 pF
Rs	=	2.5 kΩ
Conversion Error	≤	1/2 LSb
V_{DD}	=	5V → Rss = 2 kΩ
Temperature	=	85°C (system max.)

EQUATION 21-1: ACQUISITION TIME

$$T_{ACQ} = \text{Amplifier Settling Time} + \text{Holding Capacitor Charging Time} + \text{Temperature Coefficient}$$
$$= T_{AMP} + T_C + T_{COFF}$$

EQUATION 21-2: A/D MINIMUM CHARGING TIME

$$V_{HOLD} = (V_{REF} - (V_{REF}/2048)) \bullet (1 - e^{(-T_C/C_{HOLD}(R_{IC} + R_{SS} + R_S))})$$
or
$$T_C = -(C_{HOLD})(R_{IC} + R_{SS} + R_S)\ln(1/2048)$$

EQUATION 21-3: CALCULATING THE MINIMUM REQUIRED ACQUISITION TIME

$T_{ACQ} = T_{AMP} + T_C + T_{COFF}$

$T_{AMP} = 0.2\ \mu s$

$T_{COFF} = (\text{Temp} - 25°C)(0.02\ \mu s/°C)$
$(85°C - 25°C)(0.02\ \mu s/°C)$
$1.2\ \mu s$

Temperature coefficient is only required for temperatures > 25°C. Below 25°C, T_{COFF} = 0 ms.

$T_C = -(C_{HOLD})(R_{IC} + R_{SS} + R_S)\ln(1/2047)\ \mu s$
$-(25\ pF)(1\ k\Omega + 2\ k\Omega + 2.5\ k\Omega)\ln(0.0004883)\ \mu s$
$1.05\ \mu s$

$T_{ACQ} = 0.2\ \mu s + 1\ \mu s + 1.2\ \mu s$
$2.4\ \mu s$

24.0 HIGH/LOW-VOLTAGE DETECT (HLVD)

The PIC18F8722 family of devices have a High/Low-Voltage Detect module (HLVD). This is a programmable circuit that allows the user to specify both a device voltage trip point and the direction of change from that point. If the device experiences an excursion past the trip point in that direction, an interrupt flag is set. If the interrupt is enabled, the program execution will branch to the interrupt vector address and the software can then respond to the interrupt.

The High/Low-Voltage Detect Control register (Register 24-1) completely controls the operation of the HLVD module. This allows the circuitry to be "turned off" by the user under software control, which minimizes the current consumption for the device.

The block diagram for the HLVD module is shown in Figure 24-1.

REGISTER 24-1: HLVDCON: HIGH/LOW-VOLTAGE DETECT CONTROL REGISTER

R/W-0	U-0	R-0	R/W-0	R/W-0	R/W-1	R/W-0	R/W-1
VDIRMAG	—	IRVST	HLVDEN	HLVDL3(1)	HLVDL2(1)	HLVDL1(1)	HLVDL0(1)
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 **VDIRMAG:** Voltage Direction Magnitude Select bit
1 = Event occurs when voltage equals or exceeds trip point (HLVDL<3:0>)
0 = Event occurs when voltage equals or falls below trip point (HLVDL<3:0>)

bit 6 **Unimplemented:** Read as '0'

bit 5 **IRVST:** Internal Reference Voltage Stable Flag bit
1 = Indicates that the voltage detect logic will generate the interrupt flag at the specified voltage range
0 = Indicates that the voltage detect logic will not generate the interrupt flag at the specified voltage range and the HLVD interrupt should not be enabled

bit 4 **HLVDEN:** High/Low-Voltage Detect Power Enable bit
1 = HLVD enabled
0 = HLVD disabled

bit 3-0 **HLVDL<3:0>:** Voltage Detection Limit bits(1)
1111 = External analog input is used (input comes from the HLVDIN pin)
1110 = Maximum setting
.
.
.
0000 = Minimum setting

Note 1: See Table 28-4 for specifications.

MOVLW **Move Literal to W**

Syntax: MOVLW k

Operands: $0 \le k \le 255$

Operation: $k \rightarrow W$

Status Affected: None

Encoding:

0000	1110	kkkk	kkkk

Description: The eight-bit literal ‘k’ is loaded into W.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read literal ‘k’	Process Data	Write to W

Example: MOVLW 5Ah

After Instruction
W = 5Ah

MOVWF **Move W to f**

Syntax: MOVWF f {,a}

Operands: $0 \le f \le 255$
$a \in [0,1]$

Operation: $(W) \rightarrow f$

Status Affected: None

Encoding:

0110	111a	ffff	ffff

Description: Move data from W to register ‘f’. Location ‘f’ can be anywhere in the 256-byte bank.

If ‘a’ is ‘0’, the Access Bank is selected. If ‘a’ is ‘1’, the BSR is used to select the GPR bank (default).

If ‘a’ is ‘0’ and the extended instruction set is enabled, this instruction operates in Indexed Literal Offset Addressing mode whenever $f \le 95$ (5Fh). See **Section 26.2.3 “Byte-Oriented and Bit-Oriented Instructions in Indexed Literal Offset Mode”** for details.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register ‘f’	Process Data	Write register ‘f’

Example: MOVWF REG, 0

Before Instruction
W = 4Fh
REG = FFh
After Instruction
W = 4Fh
REG = 4Fh

28.2 DC Characteristics: Power-Down and Supply Current PIC18F6X27/6X22/8X27/8X22 (Industrial, Extended) PIC18LF6X27/6X22/8X27/8X22 (Industrial) (Continued)

PIC18LF6X27/6X22/8X27/8X22 (Industrial)		**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial					
PIC18F6X27/6X22/8X27/8X22 (Industrial, Extended)		**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended					
Param No.	**Device**	**Typ**	**Max**	**Units**	**Conditions**		
	Supply Current (IDD)(2)						
	PIC18LF6X27/6X22/8X27/8X22	1.0	1.3	mA	-40°C	VDD = 2.0V	FOSC = 4 MHz (**RC_RUN** mode, Internal oscillator source)
		1.0	1.3	mA	+25°C		
		1.0	1.3	mA	+85°C		
	PIC18LF6X27/6X22/8X27/8X22	1.6	1.9	mA	-40°C	VDD = 3.0V	
		1.6	1.9	mA	+25°C		
		1.6	1.9	mA	+85°C		
	All devices	3.0	3.5	mA	-40°C	VDD = 5.0V	
		3.0	3.4	mA	+25°C		
		3.0	3.4	mA	+85°C		
	Extended devices only	3.0	3.4	mA	+125°C		
	PIC18LF6X27/6X22/8X27/8X22	3.5	5	µA	-40°C	VDD = 2.0V	FOSC = 31 kHz (**RC_IDLE** mode, Internal oscillator source)
		3.7	5	µA	+25°C		
		4.3	9.5	µA	+85°C		
	PIC18LF6X27/6X22/8X27/8X22	5.4	7	µA	-40°C	VDD = 3.0V	
		5.7	8	µA	+25°C		
		7.0	15	µA	+85°C		
	All devices	11	15	µA	-40°C	VDD = 5.0V	
		11.8	15	µA	+25°C		
		13.5	35	µA	+85°C		
	Extended devices only	25	200	µA	+125°C		

Legend: Shading of rows is to assist in readability of the table.

Note 1: The power-down current in Sleep mode does not depend on the oscillator type. Power-down current is measured with the part in Sleep mode, with all I/O pins in high-impedance state and tied to VDD or VSS and all features that add delta current disabled (such as WDT, Timer1 Oscillator, BOR, etc.).

2: The supply current is mainly a function of operating voltage, frequency and mode. Other factors, such as I/O pin loading and switching rate, oscillator type and circuit, internal code execution pattern and temperature, also have an impact on the current consumption.
The test conditions for all IDD measurements in active operation mode are:
OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VDD OR VSS;
$\overline{MCLR}$ = VDD; WDT enabled/disabled as specified.

3: When operation below -10°C is expected, use T1OSC High-Power mode, where LPT1OSC (CONFIG3H<2>) = 0. When operation will always be above -10°C, then the low-power Timer1 oscillator may be selected.

4: BOR and HLVD enable internal band gap reference. With both modules enabled, current consumption will be less than the sum of both specifications.

TABLE 28-1: MEMORY PROGRAMMING REQUIREMENTS

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial				
Param No.	**Sym**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
		Data EEPROM Memory					
D120	ED	Byte Endurance	100K	1M	—	E/W	-40°C to +85°C
D121	VDRW	VDD for Read/Write	VMIN	—	5.5	V	Using EECON to read/write VMIN = Minimum operating voltage
D122	TDEW	Erase/Write Cycle Time	—	4	—	ms	
D123	TRETD	Characteristic Retention	40	—	—	Year	Provided no other specifications are violated
D124	TREF	Number of Total Erase/Write Cycles before Refresh(1)	1M	10M	—	E/W	-40°C to +85°C
D125	IDDP	Supply Current during Programming	—	10	—	mA	
		Program Flash Memory					
D130	EP	Cell Endurance	10K	100K	—	E/W	-40°C to +85°C
D131	VPR	VDD for Read	VMIN	—	5.5	V	VMIN = Minimum operating voltage
D132B	VPEW	VDD for Self-Timed Write and Row Erase	VMIN	—	5.5	V	VMIN = Minimum operating voltage
D133A	TIW	Self-Timed Write Cycle Time	—	2	—	ms	
D134	TRETD	Characteristic Retention	40	100	—	Year	Provided no other specifications are violated
D135	IDDP	Supply Current during Programming	—	10	—	mA	

† Data in “Typ” column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Refer to **Section 8.8 “Using the Data EEPROM”** for a more detailed discussion on data EEPROM endurance.

TABLE 28-2: COMPARATOR SPECIFICATIONS

Operating Conditions: 3.0V < V_{DD} < 5.5V, -40°C < T_A < +85°C (unless otherwise stated)							
Param No.	**Sym**	**Characteristics**	**Min**	**Typ**	**Max**	**Units**	**Comments**
D300	V_{IOFF}	Input Offset Voltage	—	±5.0	±10	mV	
D301	V_{ICM}	Input Common Mode Voltage	0	—	V_{DD} – 1.5	V	
D302	CMRR	Common Mode Rejection Ratio	55	—	—	dB	
300	T_{RESP}	Response Time(1)	—	150	400	ns	PIC18**F**XXXX
300A			—	150	600	ns	PIC18**LF**XXXX, V_{DD} = 2.0V
301	T_{MC2OV}	Comparator Mode Change to Output Valid	—	—	10	µs	

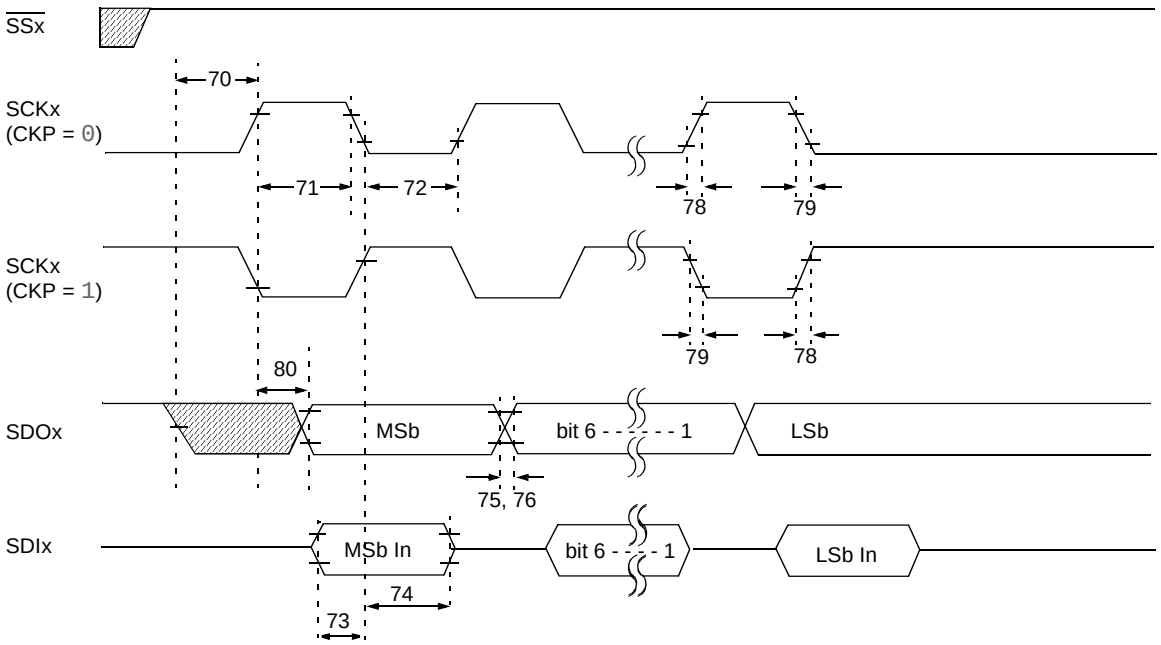
Note 1: Response time measured with one comparator input at (V_{DD} – 1.5)/2, while the other input transitions from V_{SS} to V_{DD}.

TABLE 28-3: COMPARATOR VOLTAGE REFERENCE SPECIFICATIONS

Operating Conditions: 3.0V < V_{DD} < 5.5V, -40°C < T_A < +85°C (unless otherwise stated)							
Param No.	**Sym**	**Characteristics**	**Min**	**Typ**	**Max**	**Units**	**Comments**
D310	V_{RES}	Resolution	V_{DD}/24	—	V_{DD}/32	LSb	
D311	V_{RAA}	Absolute Accuracy	—	—	1/2	LSb	
D312	V_{RUR}	Unit Resistor Value (R)	—	2k	—	Ω	
310	T_{SET}	Settling Time(1)	—	—	10	µs	

Note 1: Settling time measured while CVRR = 1 and CVR<3:0> transitions from '0000' to '1111'.

FIGURE 28-15: EXAMPLE SPI MASTER MODE TIMING (CKE = 0)



Note: Refer to Figure 28-5 for load conditions.

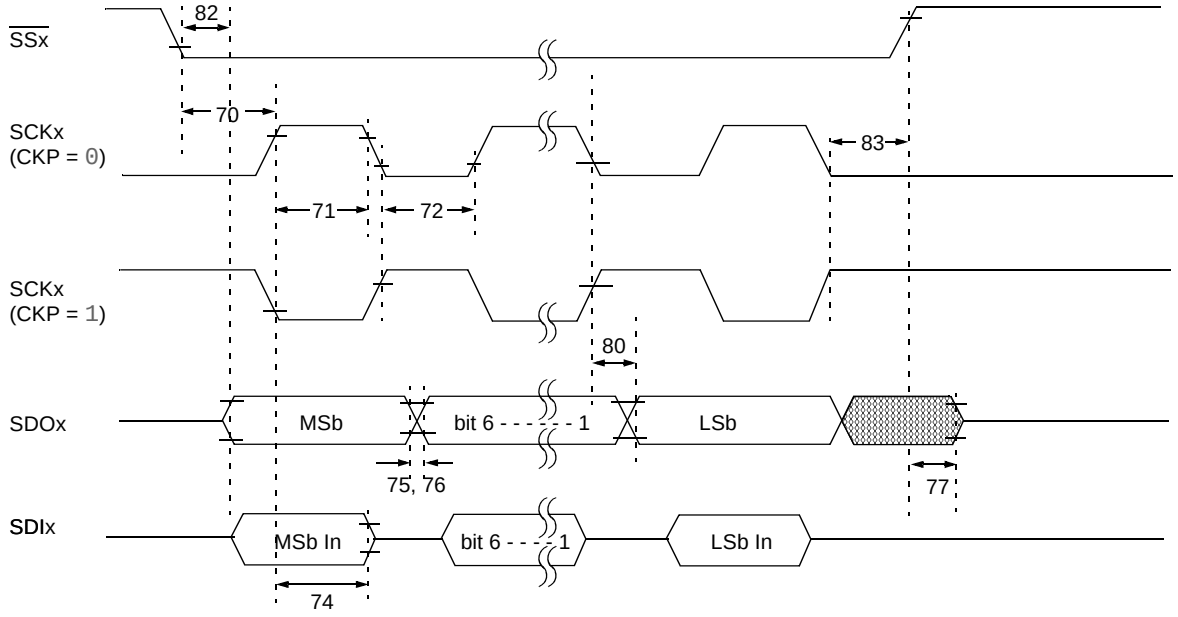
TABLE 28-16: EXAMPLE SPI MODE REQUIREMENTS (MASTER MODE, CKE = 0)

Param No.	Symbol	Characteristic		Min	Max	Units	Conditions
70	TssL2scH, TssL2scL	$\overline{SSx}$ ↓ to SCKx ↓ or SCKx ↑ Input		Tcy	—	ns	
71	TscH	SCKx Input High Time (Slave mode)	Continuous	1.25 Tcy + 30	—	ns	
71A			Single Byte	40	—	ns	**(Note 1)**
72	TscL	SCKx Input Low Time (Slave mode)	Continuous	1.25 Tcy + 30	—	ns	
72A			Single Byte	40	—	ns	**(Note 1)**
73	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge		20	—	ns	
73A	Tb2b	Last Clock Edge of Byte 1 to the 1st Clock Edge of Byte 2		1.5 Tcy + 40	—	ns	**(Note 2)**
74	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge		40	—	ns	
75	TdoR	SDOx Data Output Rise Time	PIC18**F**XXXX	—	25	ns	
			PIC18**LF**XXXX	—	45	ns	VDD = 2.0V
76	TdoF	SDOx Data Output Fall Time		—	25	ns	
78	TscR	SCKx Output Rise Time (Master mode)	PIC18**F**XXXX	—	25	ns	
			PIC18**LF**XXXX	—	45	ns	VDD = 2.0V
79	TscF	SCKx Output Fall Time (Master mode)		—	25	ns	
80	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	PIC18**F**XXXX	—	50	ns	
			PIC18**LF**XXXX	—	100	ns	VDD = 2.0V

Note 1: Requires the use of Parameter #73A.

2: Only if Parameter #71A and #72A are used.

FIGURE 28-18: EXAMPLE SPI SLAVE MODE TIMING (CKE = 1)



Note: Refer to Figure 28-5 for load conditions.

TABLE 28-19: EXAMPLE SPI SLAVE MODE REQUIREMENTS (CKE = 1)

Param No.	Symbol	Characteristic		Min	Max	Units	Conditions
70	TssL2scH, TssL2scL	$\overline{SSx}$ ↓ to SCKx ↓ or SCKx ↑ Input		3 TCY	—	ns	
71	TscH	SCKx Input High Time (Slave mode)	Continuous	1.25 TCY + 30	—	ns	
71A			Single Byte	40	—	ns	**(Note 1)**
72	TscL	SCKx Input Low Time (Slave mode)	Continuous	1.25 TCY + 30	—	ns	
72A			Single Byte	40	—	ns	**(Note 1)**
73A	TB2B	Last Clock Edge of Byte 1 to the First Clock Edge of Byte 2		1.5 TCY + 40	—	ns	**(Note 2)**
74	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge		40	—	ns	
75	TdoR	SDOx Data Output Rise Time	PIC18**F**XXXX	—	25	ns	
			PIC18**LF**XXXX	—	45	ns	VDD = 2.0V
76	TdoF	SDOx Data Output Fall Time		—	25	ns	
77	TssH2doZ	$\overline{SSx}$ ↑ to SDOx Output High-Impedance		10	50	ns	
78	TscR	SCKx Output Rise Time (Master mode)	PIC18**F**XXXX	—	25	ns	
			PIC18**LF**XXXX	—	45	ns	VDD = 2.0V
79	TscF	SCKx Output Fall Time (Master mode)		—	25	ns	
80	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	PIC18**F**XXXX	—	50	ns	
			PIC18**LF**XXXX	—	100	ns	VDD = 2.0V
82	TssL2doV	SDOx Data Output Valid after $\overline{SSx}$ ↓ Edge	PIC18**F**XXXX	—	50	ns	
			PIC18**LF**XXXX	—	100	ns	VDD = 2.0V
83	TscH2ssH, TscL2ssH	$\overline{SSx}$ ↑ after SCKx Edge		1.5 TCY + 40	—	ns	

Note 1: Requires the use of Parameter #73A.

2: Only if Parameter #71A and #72A are used.

NOTES:

PIC18F8722 FAMILY PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

PART NO.	X	/XX	XXX
Device	Temperature Range	Package	Pattern

Device	PIC18F6527/6622/6627/6722[(1)], PIC18F8527/8622/8627/8722[(1)], PIC18F6527/6622/6627/6722T[(2)], PIC18F8527/8622/8627/8722T[(2)]; V_{DD} range 4.2V to 5.5V PIC18LF6627/6722[(1)], PIC18LF8627/8722[(1)], PIC18LF6627/6722T[(2)], PIC18LF8627/8722T[(2)]; V_{DD} range 2.0V to 5.5V
Temperature Range	I = -40°C to +85°C (Industrial) E = -40°C to +125°C (Extended)
Package	PT = TQFP (Thin Quad Flatpack)
Pattern	QTP, SQTP, Code or Special Requirements (blank otherwise)

Examples:

a) PIC18LF6622-I/PT 301 = Industrial temp., TQFP package, Extended V_{DD} limits, QTP pattern #301.

b) PIC18LF6722-E/PT = Extended temp., TQFP package, standard V_{DD} limits.

Note 1: F = Standard Voltage Range
LF = Wide Voltage Range
2: T = in tape and reel TQFP packages only.